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(54) Title: SUBSTRATE ADHESION ENHANCEMENT TO FILM

(57) Abstract: The invention relates to the manufacture of printed circuit boards having improved interlayer adhesion. More particularly, the present invention pertains to adhesiveless printed circuit boards having excellent thermal performance and useful for producing high-density circuits. A metal foil is laminated to an etched surface of a polyimide substrate having a polyimide film thereon. Etching the substrate surface allows for strong adhesion of a pure polyimide film to the substrate.



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